



SOT619-23

HVQFN48, plastic, thermal enhanced very thin quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 0.85 mm body

6 June 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-05-2019
Manufacturer package code	98ASA00933D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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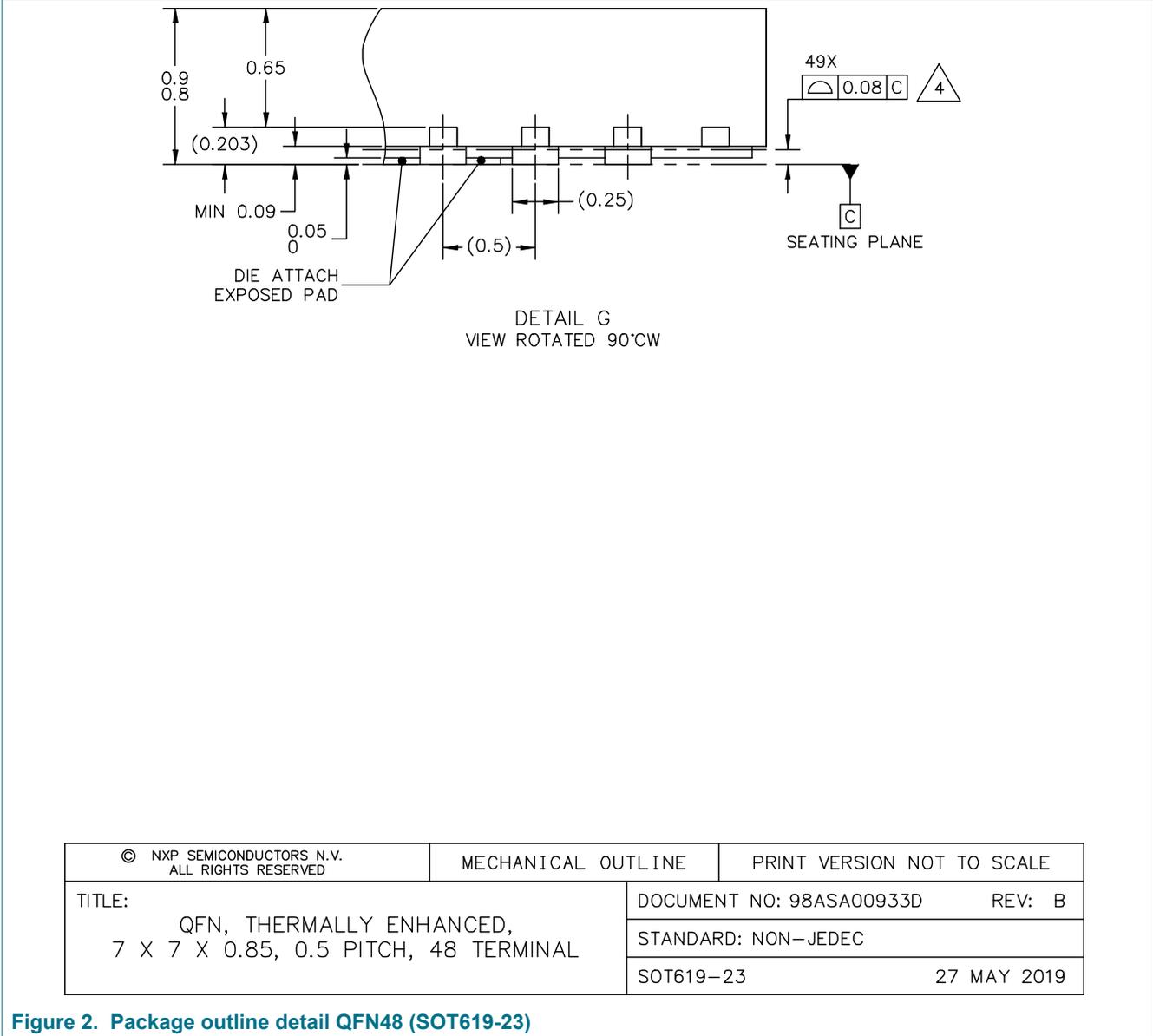


Figure 2. Package outline detail QFN48 (SOT619-23)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS, CORNER LEADS AND DIE ATTACH PAD.
5. MIN METAL GAP SHOULD BE 0.2 MM.

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TITLE: QFN, THERMALLY ENHANCED, 7 X 7 X 0.85, 0.5 PITCH, 48 TERMINAL	DOCUMENT NO: 98ASA00933D		REV: B
	STANDARD: NON-JEDEC		
	SOT619-23		27 MAY 2019

Figure 3. Package outline note QFN48 (SOT619-23)

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3 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Legal information5